



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

APPLICANT: OH ET AL. / DOCKET NO.: WK2K1070  
SERIAL NO: 10/015,374 / EXAMINER: WILLIAMS  
FILED: 12/12/2001 / ART UNIT: 2826  
TITLE: STACKING STRUCTURE OF SEMICONDUCTOR CHIPS AND SEMICONDUCTOR PACKAGE USING IT

#10K  
Amody  
J. Mcmin  
6/6/03

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Weiss, Moy & Harris, P.C.  
4204 N. Brown Avenue  
Scottsdale, AZ 85251-3989

May 15, 2003

I hereby certify that on the 15<sup>th</sup> day of May, 2003, this correspondence is being deposited with the U.S. Postal Service as first class mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450 Alexandria, 22313-1450.

  
Jeffrey D. Moy

AMENDMENT

Dear Sir:

This is in response to the Office Action dated January 15, 2003 in regards to the above identified patent application. Please amend the subject patent application as follows:

RECEIVED  
MAY 29 2003  
TECHNOLOGY CENTER 2800